AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A method comprising:

creating an exposure image in a radiation sensitive layer by exposing the radiation sensitive layer to radiation; and

modifying the exposure image by treating the exposure image with a [[substantially]] heterogeneous thermal treatment.

2. (Currently Amended) The method of claim 1[[, wherein]]:

wherein creating the exposure image comprises creating a first exposure feature contained in a first region and creating a second exposure feature contained in a second region; and

wherein modifying the exposure image comprises treating the first region with a first thermal flux and treating the second region with a second [[substantially]] different thermal flux.

3. (Currently Amended) The method of claim 1, [[wherein modifying the exposure feature]] further comprising [[comprises]] specifying the heterogeneous thermal treatment by adjusting a height adjustable spacer.

4. (Currently Amended) The method of claim 1:

wherein creating the exposure image comprises creating a first critical dimension having an undersizing error and creating a second critical dimension having an oversizing error; and

wherein modifying the exposure image [[further]] comprises reducing the undersizing error by [[increasing a temperature of]] heating the first critical dimension to a first temperature [[by a first amount]] at a particular time and [[increasing a temperature of]] heating the second critical dimension [[by a second amount]] to a second temperature that is less than the first temperature [[amount]] at the particular time.

5. – 21. (Canceled)

22. (New) The method of claim 3, wherein adjusting the height adjustable spacer comprises turning a screw.

23. (New) The method of claim 3, wherein adjusting the height adjustable spacer comprises changing a voltage input to a piezoelectric substance.

24. (New) The method of claim 1, further comprising, prior to said modifying, specifying the heterogeneous thermal treatment by adjusting a plurality of height-adjustable spacers to different heights.

25. (New) The method of claim 1, wherein modifying the exposure image comprises performing position variant chemical transformation of the exposure image in a chemically amplified resist.

26. (New) The method of claim 1, wherein modifying the exposure image comprises reducing an error of the exposure image.

27. (New) The method of claim 1, wherein modifying the exposure image comprises modifying a size of a critical dimension of the exposure image.

28. (New) A method comprising:

applying a radiation sensitive layer to a substrate by spin coating;

increasing a temperature of the applied layer by heating;

after said heating, creating an exposure image in the layer by exposing the layer to patterned radiation; and

modifying the exposure image by treating the exposure image with a non-uniform thermal treatment.

29. (New) The method of claim 28, further comprising:

developing the modified exposure image by contacting the layer with a developer; and

after said developing, etching a material of the substrate.

30. (New) The method of claim 28, further comprising, prior to said modifying, specifying the non-uniform thermal treatment by adjusting a height-adjustable spacer.

31. (New) The method of claim 30, wherein adjusting the height adjustable spacer comprises turning a screw.

32. (New) The method of claim 30, wherein adjusting the height adjustable spacer comprises changing a voltage input to a piezoelectric substance.

33. (New) The method of claim 28, further comprising, prior to said modifying, specifying the non-uniform thermal treatment by adjusting a plurality of height-adjustable spacers to a plurality of different heights.

34. (New) The method of claim 28, wherein modifying the exposure image comprises performing position variant chemical transformation of the exposure image in a chemically amplified resist.

35. (New) The method of claim 28, wherein modifying the exposure image comprises reducing an error of the exposure image.

36. (New) The method of claim 28, wherein modifying the exposure image comprises modifying a size of a critical dimension of the exposure image.